

Supplementary Information

Direct adhesion between Cu foil and polytetrafluoroethylene without increasing surface roughness for high-frequency printed wiring boards

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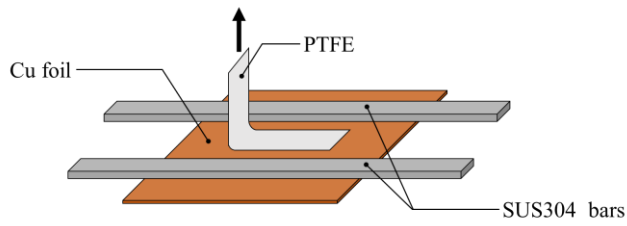


Fig. S1 Schematic of 90° peel test.

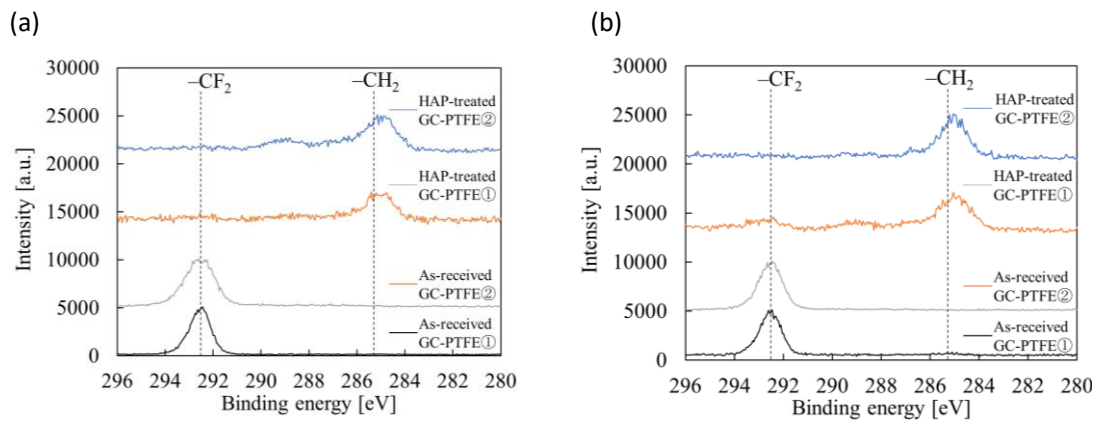


Fig. S2 C1s-XPS spectra of peeling interface of Cu/GC-PTFE: (a) PTFE side; (b) Cu side.

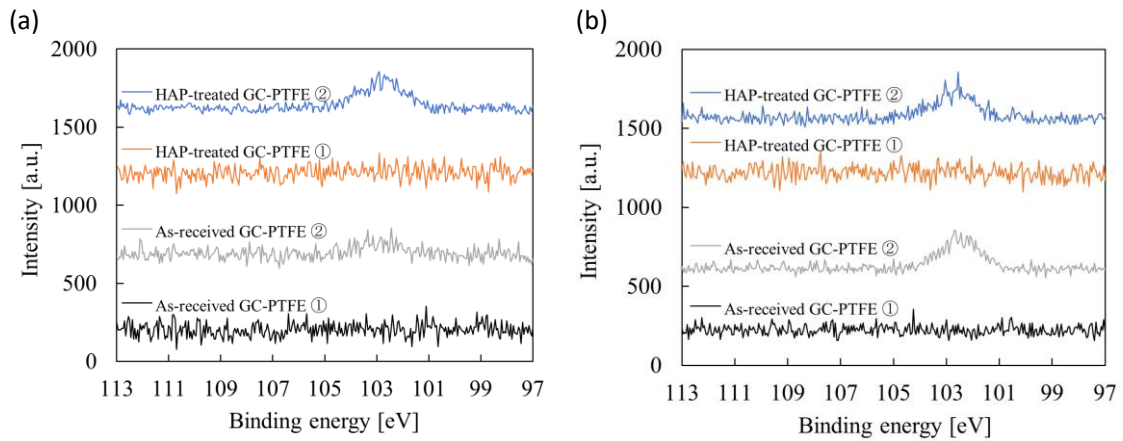


Fig. S3 Si2p-XPS spectra of peeling interface of Cu/GC-PTFE: (a) PTFE side; (b) Cu side.